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PATENT NUMBER and  
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## U.S. UTILITY Patent Application

APPL NUM 10019299	FILING DATE 03/11/2002	CLASS 174	SUBCLASS 260	GAU 2841	EXAMINER A1-A1A
<b>**APPLICANTS:</b> Gotoh Johshi; Okuno Tatsuya; 252					
<b>**CONTINUING DATA VERIFIED:</b> THIS APPLICATION IS A 371 OF PCT/JP00/04490 07/06/2000 (Gotoh Johshi)					
<b>** FOREIGN APPLICATIONS VERIFIED:</b> JAPAN 194501/1999 07/08/1999					
PG-PUB <input type="checkbox"/> DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed 35 USC 119 conditions met Verified and Acknowledged Examiners's initials		<input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO P67440US0	
TITLE : Underfilling material for semiconductor package					
U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)					

<b>NOTICE OF ALLOWANCE MAILED</b>		<b>CLAIMS ALLOWED</b>	
		Total Claims	
		Print Claim for O.G.	
<b>ISSUE FEE</b>		<b>DRAWING</b>	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg.
		Print Fig.	
<input type="checkbox"/> <b>TERMINAL DISCLAIMER</b>		Application Examiner	
		<b>PREPARED FOR ISSUE</b>	
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